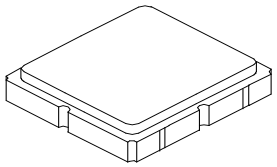
AEC-Q200
This component was always RoHS compliant from the first date of manufacture.

SF2446E

435 MHz SAW Filter



SM3030-6

Complies with Directive 2002/95/EC (RoHS)

Maximum Rating

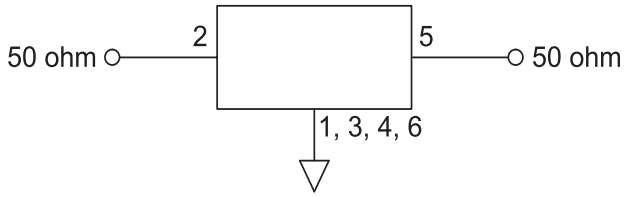
Rating	Value	Units
Input Power Level	10	dB_m
DC Voltage	10	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature in Tape and Reel	-45 to +85	°C
Moisture Sensitivity Level	1	MSL

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			435		MHz
3dB Bandwidth			10	23		MHz
Insertion Loss, 430 to 440 MHz	IL			1.9	3.0	dB
Amplitude Ripple, 430 to 440 MHz MHz				0.8	2.0	dB
Attenuation Referenced to 0 dB						dB
0.3 to 386.6 MHz			45	54		
386.6 to 396.6 MHz			46	52		
474.8 to 480.8 MHz			45	54		
480.8 to 680 MHz			45	50		
680 to 1000 MHz			35	46		
Temperature Coefficient of Frequency				-36		ppm/°C

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	B3, YWWS

Measurement Circuit



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

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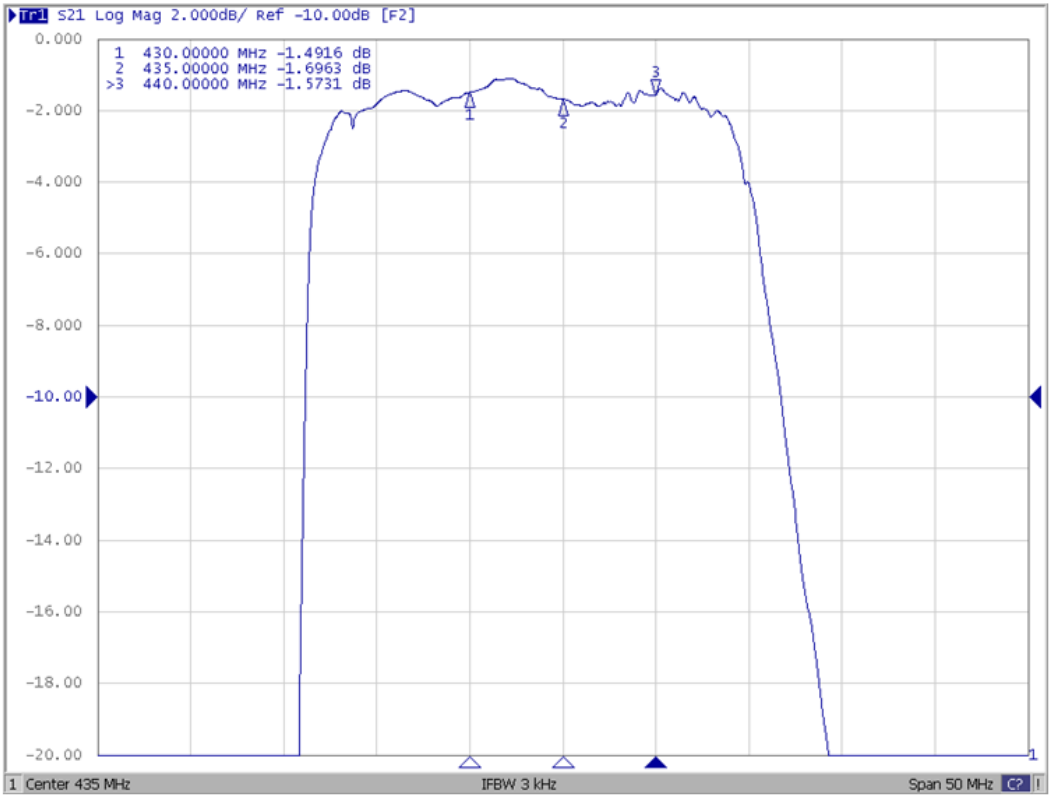
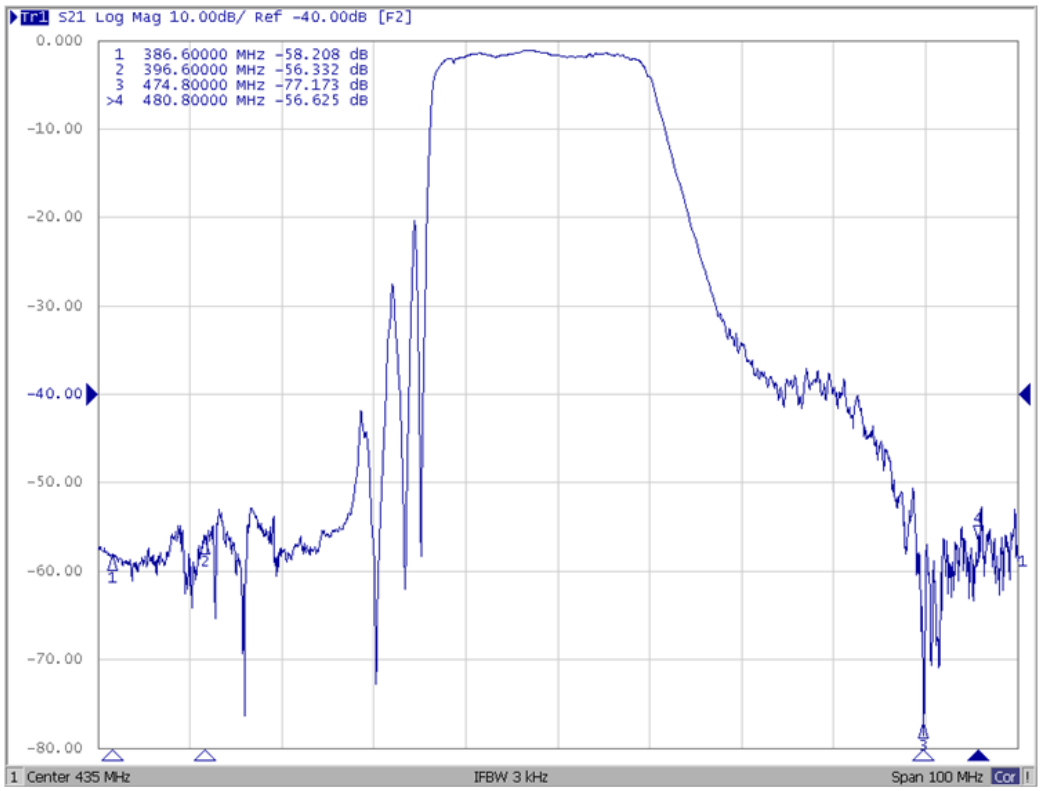
Frequency Characteristics





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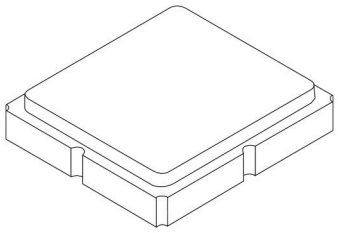
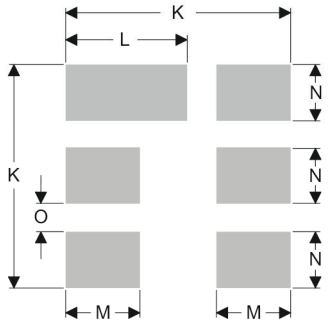
6-Terminal Ceramic Surface-Mount Case
3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

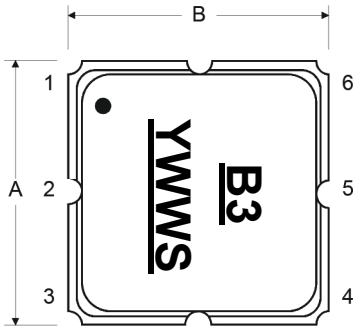
Case and PCB Footprint Dimensions

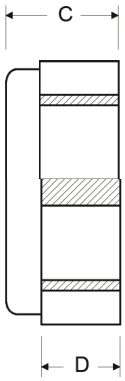
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

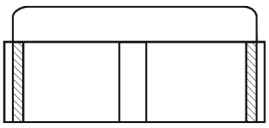
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

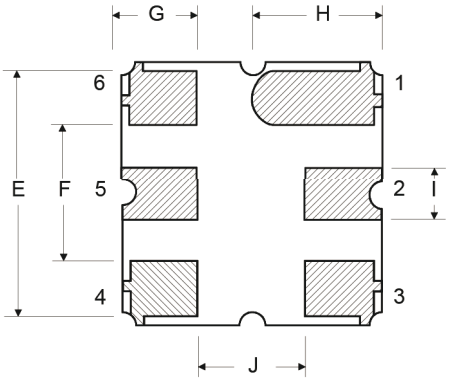
Top View







Bottom View



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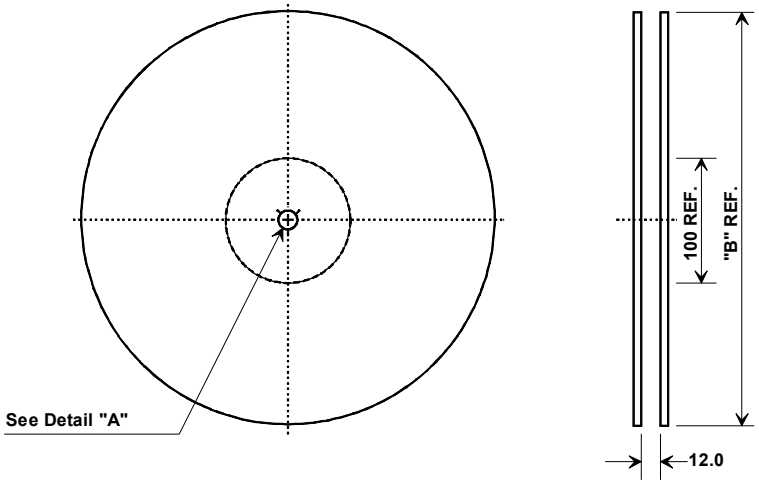
Tape and Reel Specifications

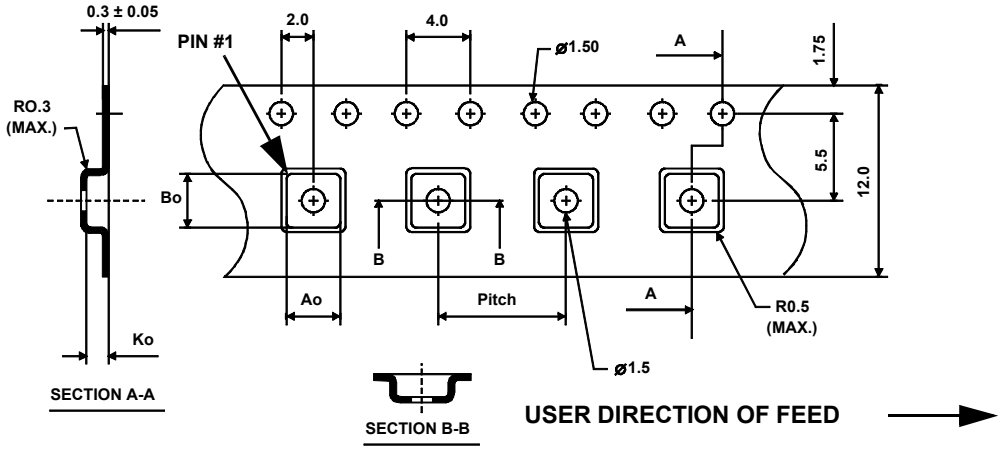


"B "		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

Tape and Reel Standard per ANSI/EIA-481

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



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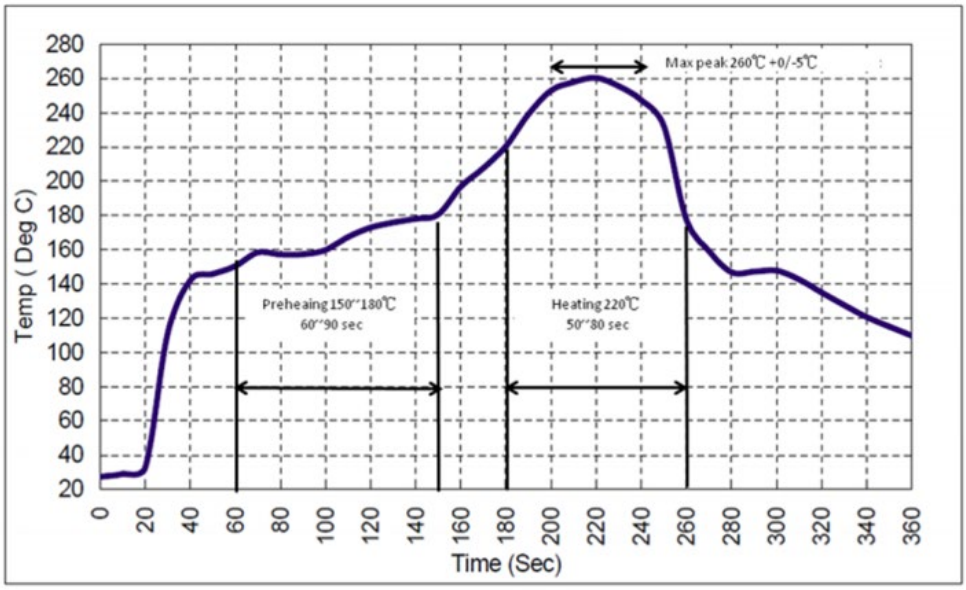
Recommended Reflow Profile

1. Preheating shall be fixed at 150~180ºC for 60~90 seconds.
2. Ascending time to preheating temperature 150ºC shall be 30 seconds min.
3. Heating shall be fixed at 220ºC for 50~80 seconds and at 260ºC +0/-5ºC peak (10 seconds).
4. Time: 5 times maximum.



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